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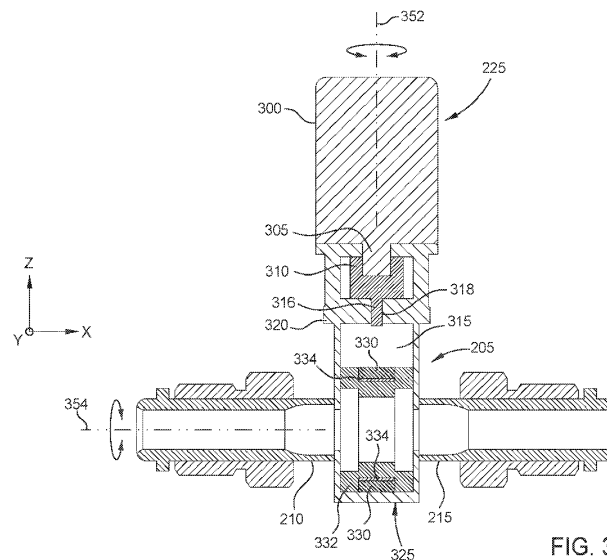


FIG. 3A

(57) Abstract: Embodiments described herein relate to a valve for semiconductor processing. The valve includes a valve body having an inlet conduit and an outlet conduit separated by a diaphragm body. The diaphragm body includes a motor, a transmission link coupled to the motor, a rotatable ring surrounding a fixed plate and separated by a dynamic seal, the rotatable ring coupled to the transmission link, and one or more shutter plates movably coupled to the rotatable ring by a respective pivotable fastener, wherein the fixed plate includes an opening and the one or more shutter plates are movable relative to the opening.

[Continued on next page]

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